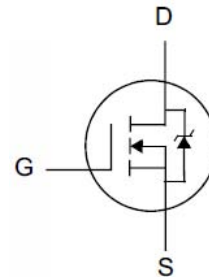




**General Features**

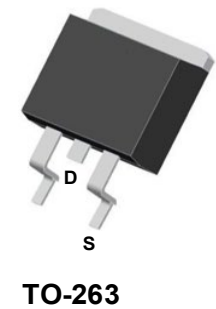
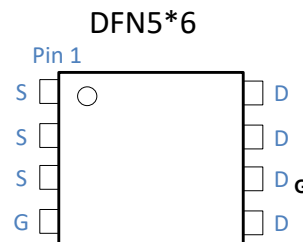
- Proprietary New Planar Technology
- $R_{DS(ON),typ.} = 45m\Omega @ V_{GS} = 10V$
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode



**Applications**

- DC-DC Converters
- DC-AC Inverters for UPS
- SMPS and Motor controls

$BV_{DSS}$	$R_{DS(ON),typ.}$	$I_D$
250V	50mΩ	50A



Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-to-Source Voltage <sup>[1]</sup>	250	V
$V_{GSS}$	Gate-to-Source Voltage	±20	
$I_D$	Continuous Drain Current	50	A
$I_{D @ T_C = 100^\circ C}$	Continuous Drain Current @ $T_C = 100^\circ C$	25	
$I_{DM}$	Pulsed Drain Current at $V_{GS} = 10V$ <sup>[2]</sup>	200	
$E_{AS}$	Single Pulse Avalanche Energy	1250	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ <sup>[3]</sup>	5.0	V/ns
$P_D$	Power Dissipation	125	W
	Derating Factor above 25°C	1.0	W/°C
$T_L$ $T_{PAK}$	Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10 seconds, Package Body for 10 seconds	300 260	°C
$T_J \& T_{STG}$	Operating and Storage Temperature Range	-55 to 150	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	100	



Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$BV_{DSS}$	Drain-to-Source Breakdown Voltage	250	--	--	V	$V_{GS}=0V, I_D=250\mu A$
$I_{DSS}$	Drain-to-Source Leakage Current	--	--	1	$\mu A$	$V_{DS}=250V, V_{GS}=0V$
		--	--	100		$V_{DS}=200V, V_{GS}=0V, T_J=125^\circ C$
$I_{GSS}$	Gate-to-Source Leakage Current	--	--	+100	$nA$	$V_{GS}=+20V, V_{DS}=0V$
		--	--	-100		$V_{GS}=-20V, V_{DS}=0V$
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance <sup>[4]</sup>	--	43	60	$m\Omega$	$V_{GS}=10V, I_D=25A$
$V_{GS(TH)}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
$g_{fs}$	Forward Transconductance <sup>[4]</sup>	--	65	--	S	$V_{DS}=15V, I_D=20A$
$C_{iss}$	Input Capacitance	--	1854	--	$pF$	$V_{GS}=0V, V_{DS}=100V, f=1.0MHz$
$C_{rss}$	Reverse Transfer Capacitance	--	7.4	--		
$C_{oss}$	Output Capacitance	--	106	--		
$Q_g$	Total Gate Charge	--	20	--	$nC$	$V_{DD}=125V, I_D=20A, V_{GS}=0 \text{ to } 10V$
$Q_{gs}$	Gate-to-Source Charge	--	7	--		
$Q_{gd}$	Gate-to-Drain (Miller) Charge	--	3	--		
$t_{d(ON)}$	Turn-on Delay Time	--	20	--	$nS$	$V_{DD}=100V, I_D=20A, V_{GS}=10V, R_G=3.9\Omega$
$t_{rise}$	Rise Time	--	30	--		
$t_{d(OFF)}$	Turn-Off Delay Time	--	65	--		
$t_{fall}$	Fall Time	--	25	--		
$I_{SD}$	Continuous Source Current <sup>[4]</sup>	--	--	50	A	Integral PN-diode in MOSFET
$I_{SM}$	Pulsed Source Current <sup>[4]</sup>	--	--	200		
$V_{SD}$	Diode Forward Voltage	--	--	1.5	V	$I_S=40A, V_{GS}=0V$
$t_{rr}$	Reverse recovery time	--	180	--	$ns$	$V_{GS}=0V, I_F=20A, di_F/dt=100A/\mu s$
$Q_{rr}$	Reverse recovery charge	--	400	--	$nC$	



Figure 1. Maximum Transient Thermal Impedance

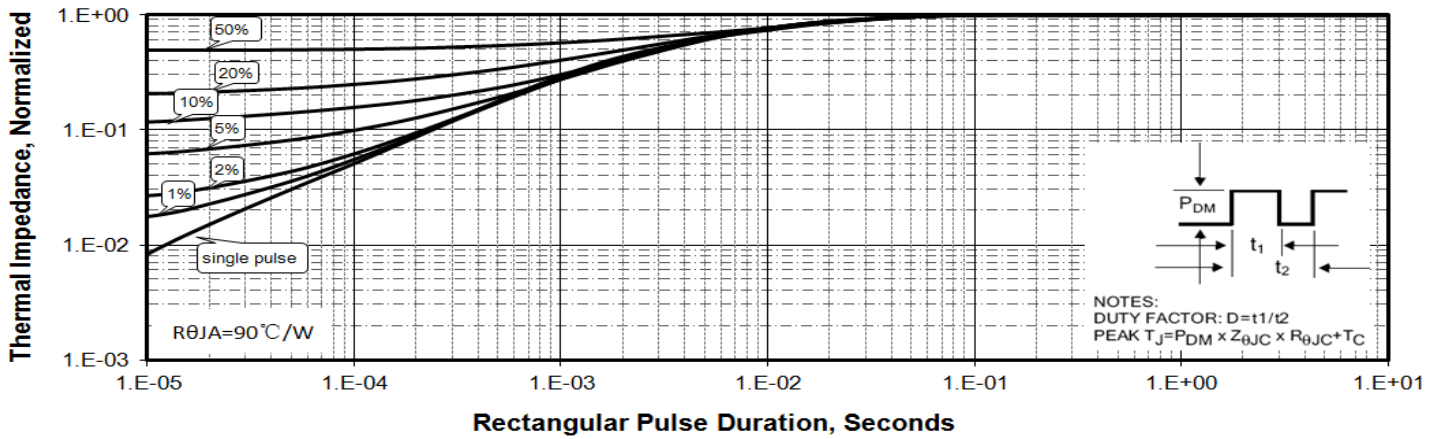


Figure 2 . Max. Power Dissipation vs Case Temperature

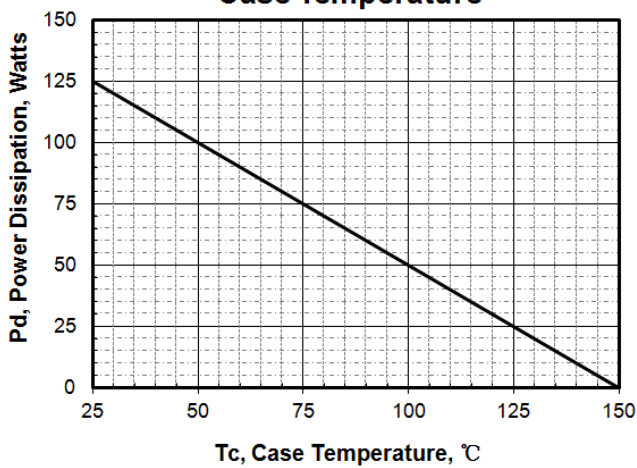


Figure 3 .Maximum Continuous Drain Current vs Tc

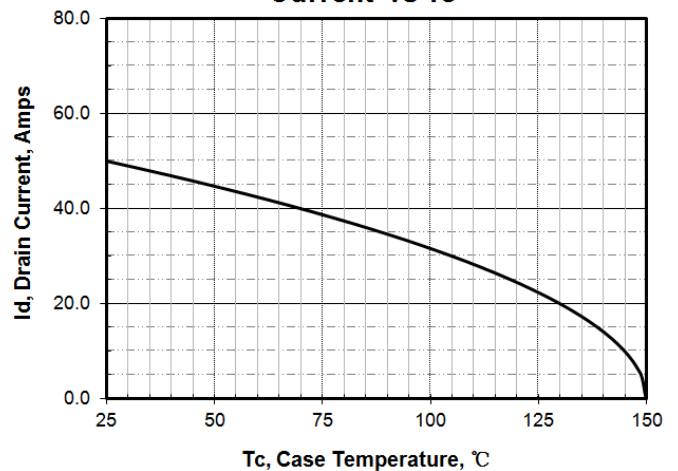


Figure 4. Output Characteristics

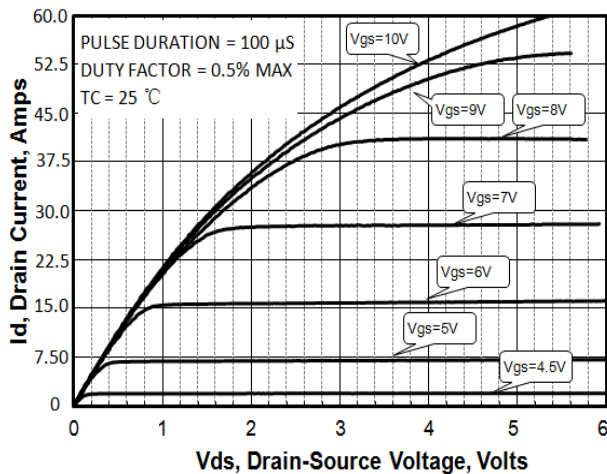


Figure 5. Rds(on) vs Gate Voltage

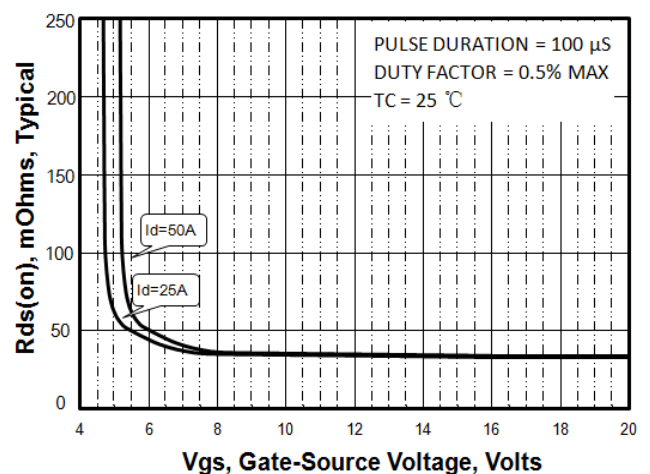




Figure 6. Peak Current Capability

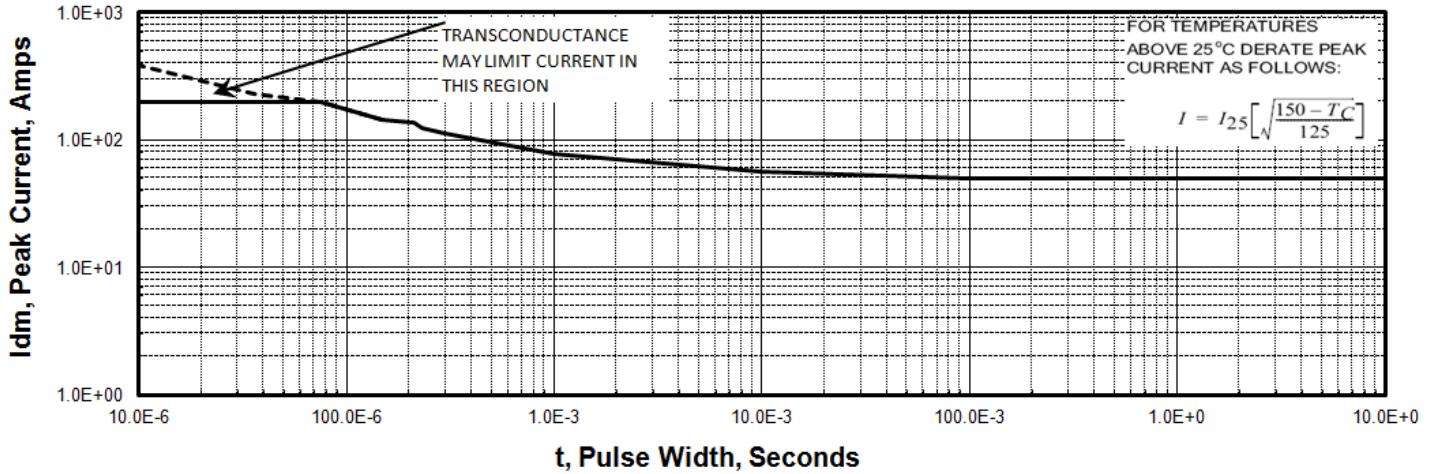


Figure 7. Transfer Characteristics

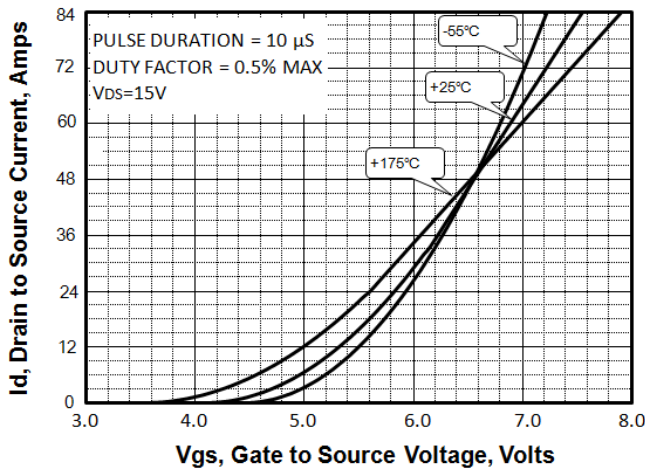


Figure 8. Unclamped Inductive Switching Capability

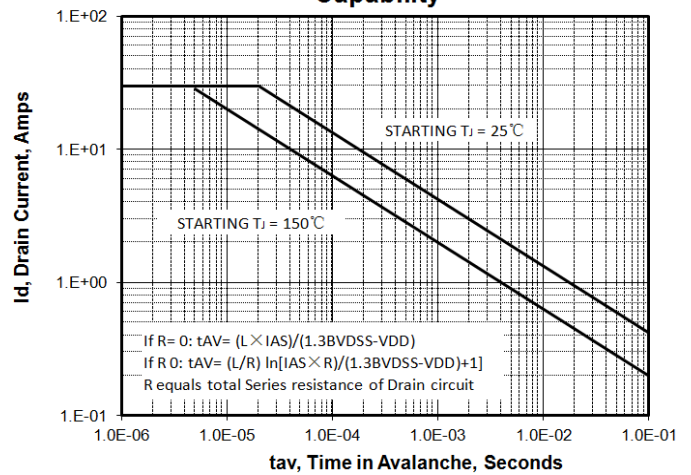


Figure 9. Drain to Source ON Resistance vs Drain Current

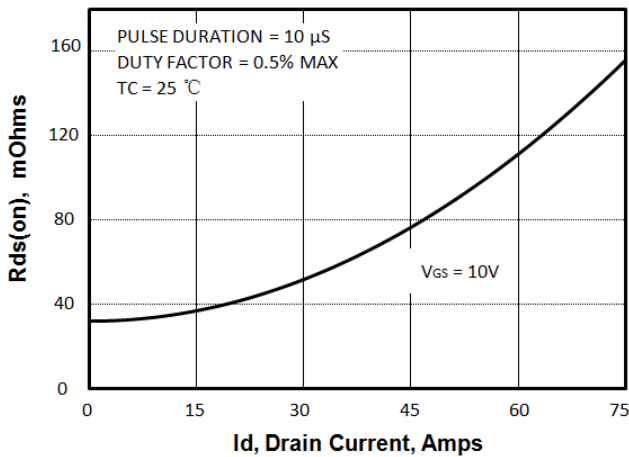


Figure 10. Rds(on) vs Junction Temperature

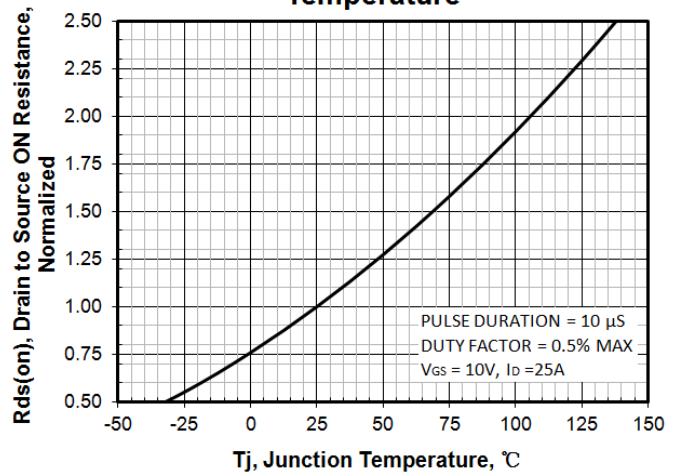




Figure 11. Typical Breakdown Voltage vs Junction Temperature

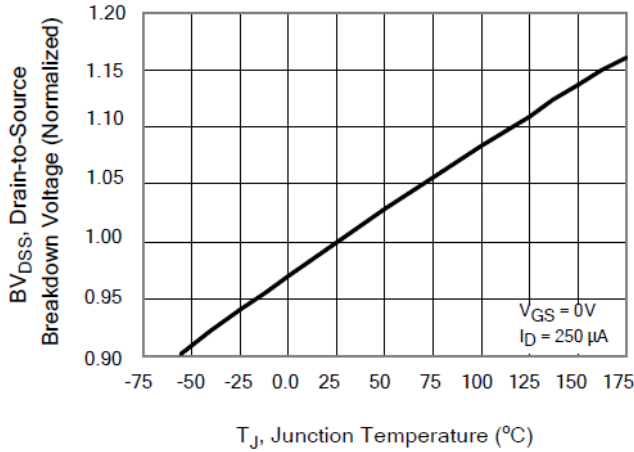


Figure 12. Typical Threshold Voltage vs Junction Temperature

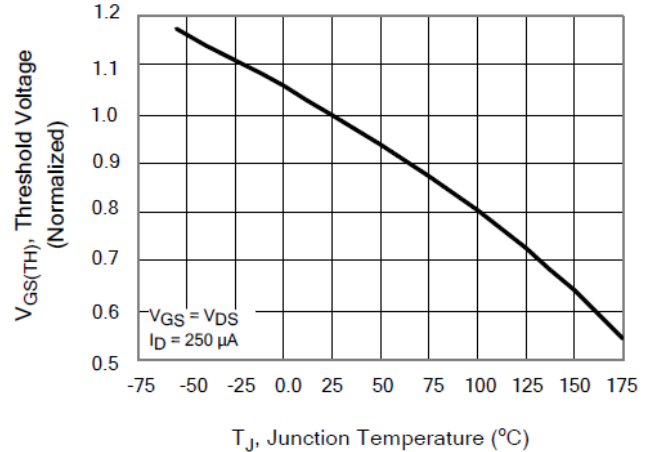


Figure 13. Maximum Safe Operating Area(TO-220F)

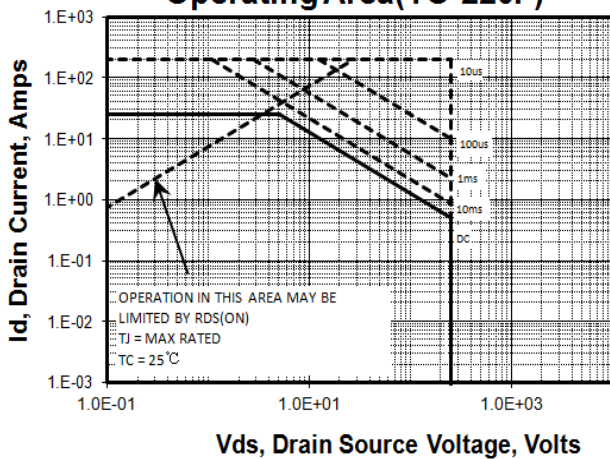


Figure 14. Capacitance vs Vds

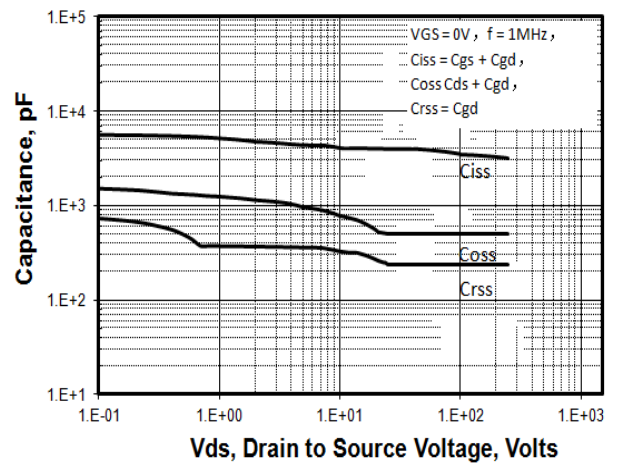


Figure 15. Typical Gate Charge

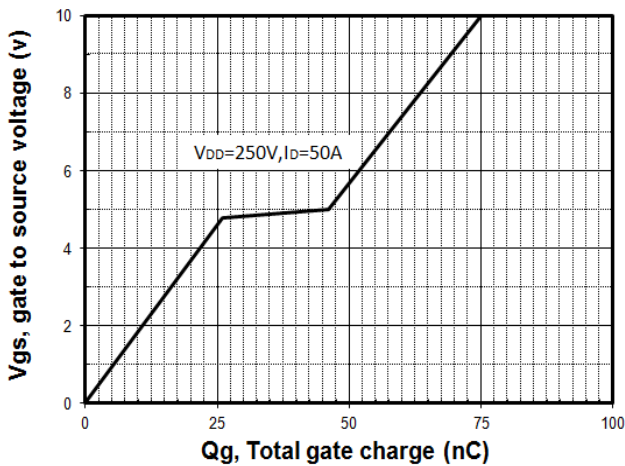
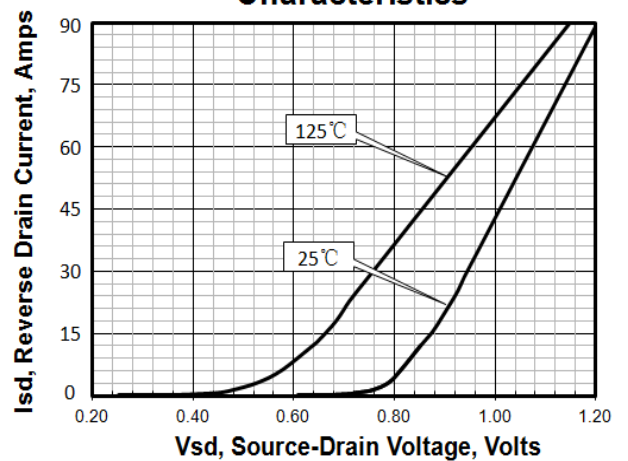


Figure 16. Body Diode Transfer Characteristics



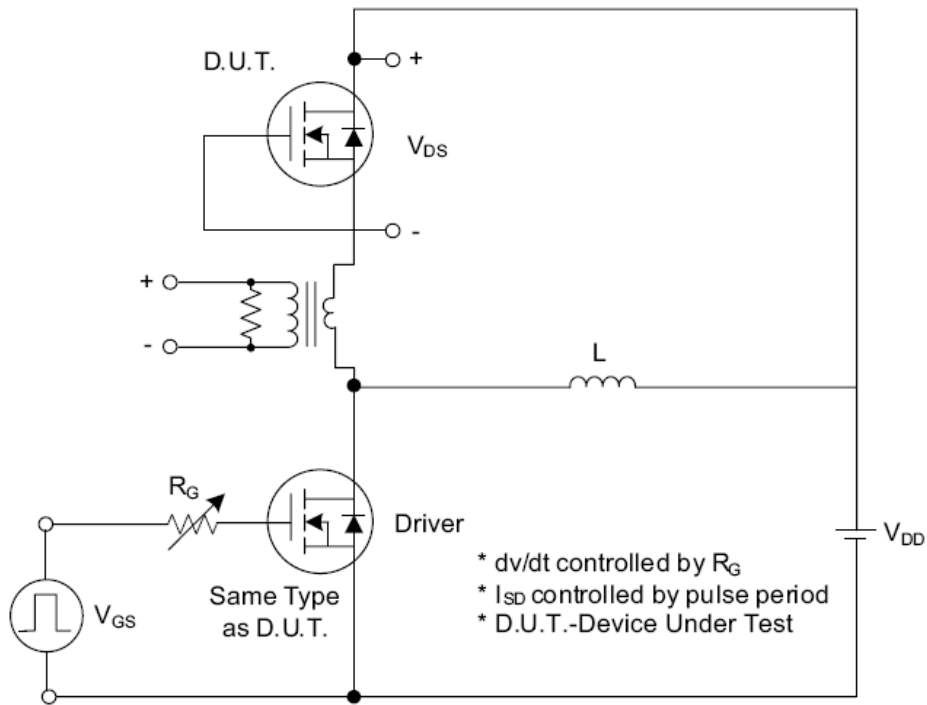


Fig. 1.1 Peak Diode Recovery  $dv/dt$  Test Circuit

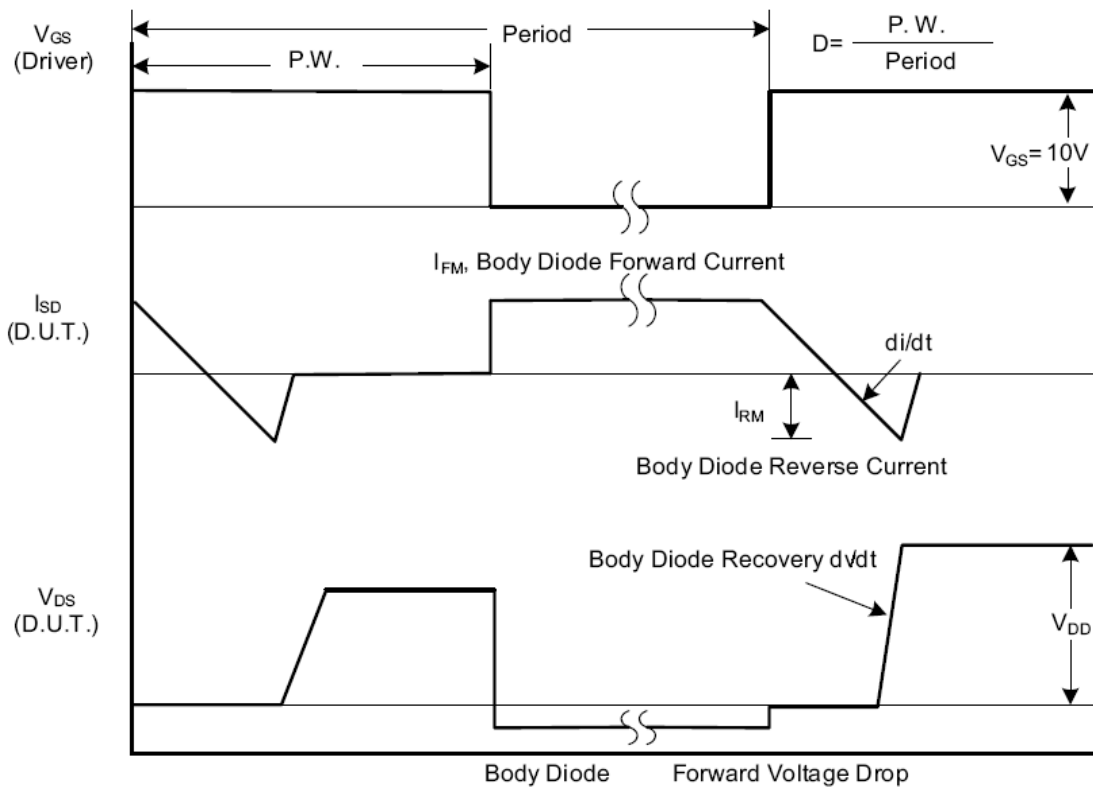


Fig. 1.2 Peak Diode Recovery  $dv/dt$  Waveforms

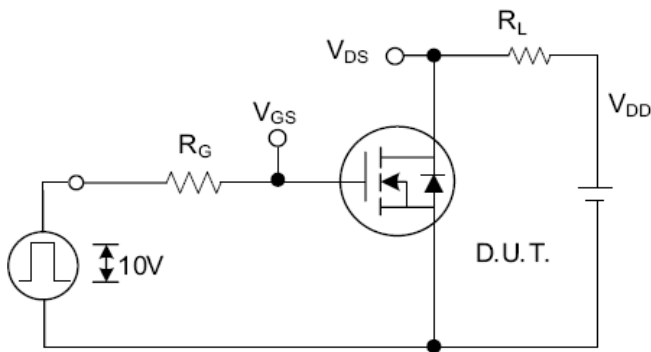


Fig. 2.1 Switching Test Circuit

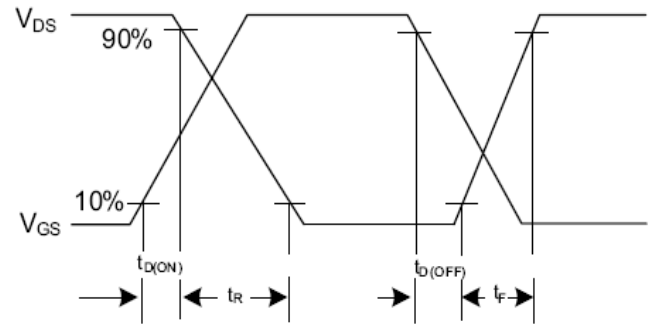


Fig. 2.2 Switching Waveforms

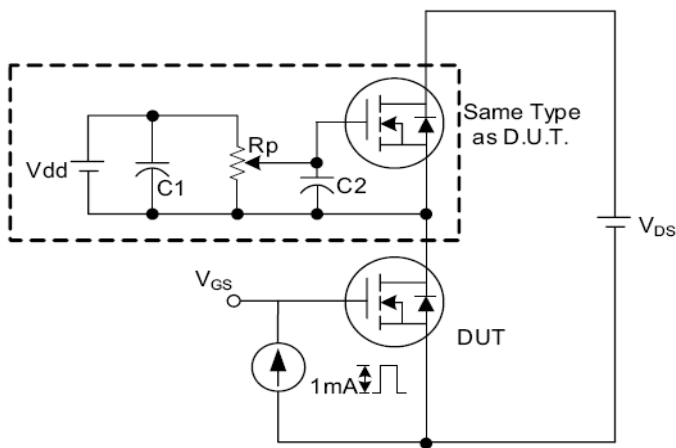


Fig. 3.1 Gate Charge Test Circuit

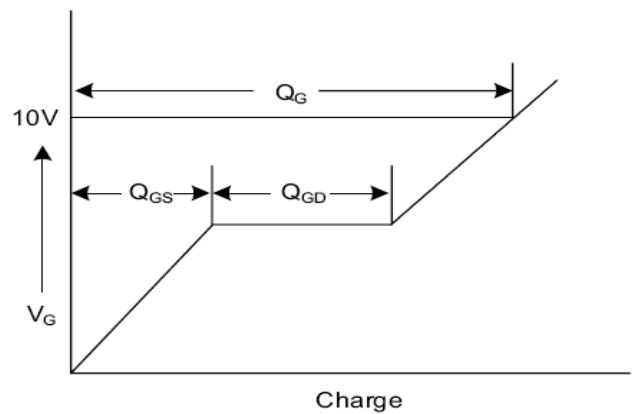


Fig. 3.2 Gate Charge Waveform

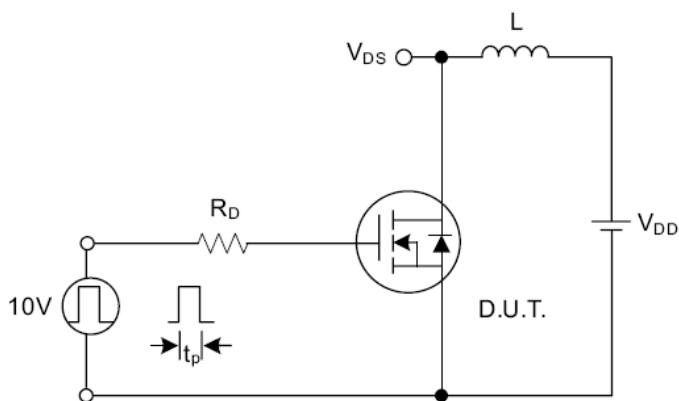


Fig. 4.1 Unclamped Inductive Switching Test Circuit

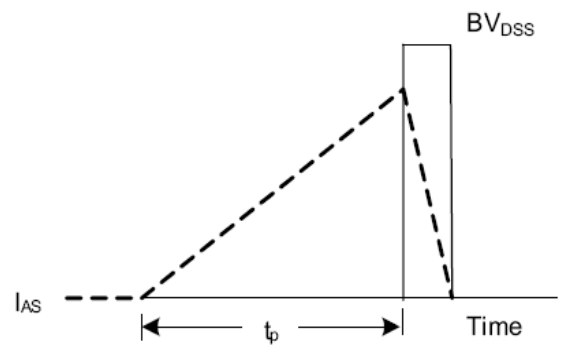
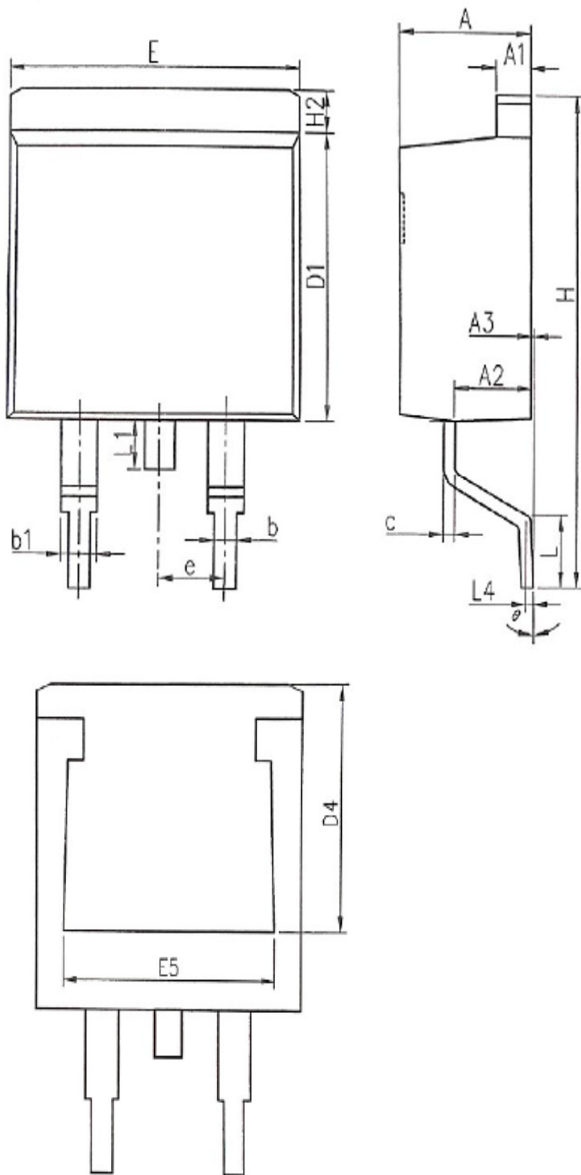


Fig. 4.2 Unclamped Inductive Switching Waveforms



**Mechanical Dimensions for TO-263**

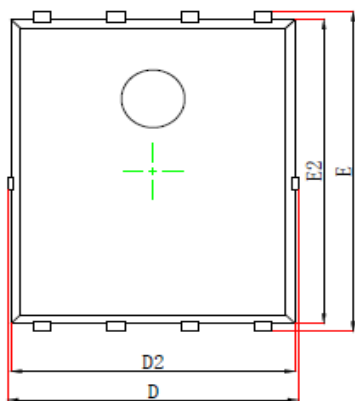
**COMMON DIMENSIONS**



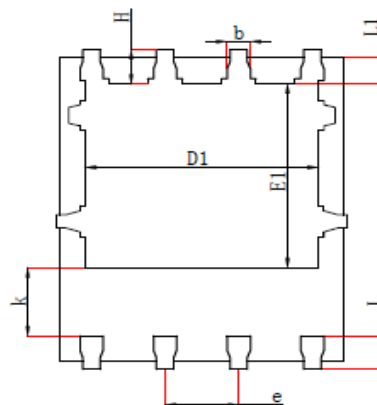
SYMBOL	MM	
	MIN	MAX
A	4.37	4.89
A1	1.17	1.42
A2	2.20	2.90
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.28	0.60
D1	8.45	9.30
D4	6.60	-
E	9.80	10.40
E5	7.06	-
e	2.54BSC	
H	14.70	15.70
H2	1.07	1.47
L	2.00	2.80
L1	-	1.75
L4	0.254BSC	
θ	0°	9°



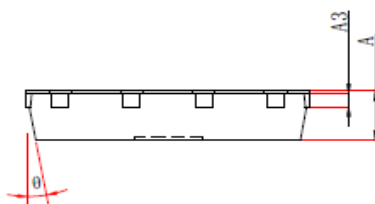
DFN5\*6, 8 leads



Top View  
[顶视图]



Bottom View  
[背视图]



Side View  
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A3	0.254 REF		0.010REF	
D	4.680	5.120	0.184	0.202
E	5.900	6.126	0.232	0.241
D1	3.610	4.110	0.142	0.162
E1	3.380	3.780	0.133	0.149
D2	4.800	5.000	0.189	0.197
E2	5.674	5.826	0.223	0.229
k	1.100	1.390	0.043	0.055
b	0.330	0.510	0.013	0.020
e	1.270TYP		1.270TYP	
L	0.510	0.711	0.020	0.028
L1	0.424	0.576	0.017	0.023
H	0.410	0.726	0.016	0.029
θ	0 <sup>0</sup>	12 <sup>0</sup>	0 <sup>0</sup>	12 <sup>0</sup>